FILM STICKING METHOD AND FILM STICKING DEVICE

ABSTRACT OF THE DISCLOSURE

There is provided a film sticking method for sticking a film on a pattern forming face of a wafer, on the pattern forming face (21) of which a circuit pattern (C) is formed, comprising the steps of: positioning the wafer (20) so that a sticking direction of a film sticking means (46) for sticking the film on the pattern forming face when the film sticking means is moved in a predetermined sticking direction (X1) on the pattern forming face of the wafer can be substantially parallel with the bisector of a corner portion of the circuit pattern; and sticking the film on the pattern forming face of the wafer when the film sticking means is moved in the sticking direction on the pattern forming face of the wafer. There is also provided a film sticking device for executing this method. Due to the foregoing, when the surface protective film is stuck, it is possible to prevent the orientation flat from being damaged and it is also possible to prevent air bubbles from being formed. When the film is peeled off after the back surface has been ground, it is preferable that the wafer is arranged in a second orientation which is rotated from the first orientation by 90°.

Fig. 3